--As the organic polymer, fluorinated polyimide was used, and as the adhesive layer, siloxylated polyimide (adhesive) was deposited in a thickness of around 500Å by spin coating before depositing the inorganic dielectric as the masking clad 4. Then, the organic waveguide was formed in accordance with the described steps.--

Please replace the paragraph beginning on page 39, line 1, with the following rewritten paragraph:

--After the organic polymer is subjected to thermal polymerization, there is a case where active functional groups on the surface may be reduced, and in particular when fluorinated polyimide is used as the organic polymer, the adhesion between the organic polymer layer and the adhesive layer becomes weak after imidization by thermal polymerization. Thus, by forming the adhesive layer before the organic polymer is subjected to thermal polymerization as described above, it is further ensured that the adhesion between the organic polymer layer and the inorganic dielectric layer is improved.--

IN THE CLAIMS:

Please cancel claims 2 and 34 without prejudice or disclaimer of any of the subject matter contained therein.